



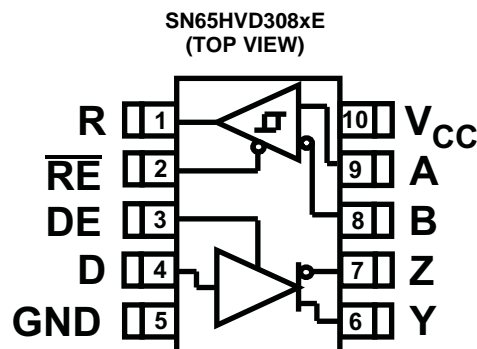
LOW-POWER RS-485 FULL-DUPLEX DRIVERS/RECEIVERS

FEATURES

- **Low Quiescent Power**
 - 375 μ A (Typical) Enabled Mode
 - 2 nA (Typical) Shutdown Mode
- **Small MSOP Package**
- **1/8 Unit-Load—Up to 256 Nodes per Bus**
- **16 kV Bus-Pin ESD Protection, 6 kV All Pins**
- **Failsafe Receiver (Bus Open, Short, Idle)**
- **TIA/EIA-485A Standard Compliant**
- **RS-422 Compatible**

APPLICATIONS

- **Motion Controllers**
- **Point-of-Sale (POS) Terminals**
- **Rack-to-Rack Communications**
- **Industrial Networks**
- **Power Inverters**
- **Battery-Powered Applications**
- **Building Automation**



DEVICE	SIGNAL RATE
SN65HVD3080E	200 kbps
SN65HVD3083E	1 Mbps
SN65HVD3086E	20 Mbps

DESCRIPTION

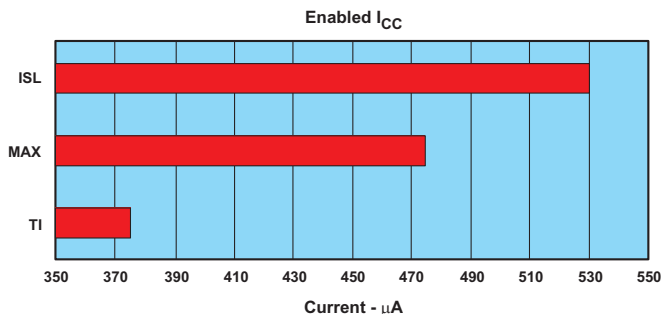
Each of these devices is a balanced driver and receiver designed for full-duplex RS-485 or RS-422 data bus networks. Powered by a 5-V supply, they are fully compliant with the TIA/EIA-485A standard.

With controlled bus output transition times, the devices are suitable for signaling rates from 200 kbps to 20 Mbps.

The devices are designed to operate with a low supply current, less than 1 mA (typical), exclusive of the load. When in the inactive shutdown mode, the supply current drops to a few nanoamps, making these devices ideal for power-sensitive applications.

The wide common-mode range and high ESD protection levels of these devices make them suitable for demanding applications such as motion controllers, electrical inverters, industrial networks, and cabled chassis interconnects where noise tolerance is essential.

These devices are characterized for operation over the temperature range -40°C to 85°C



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

PART NUMBER	PACKAGE ⁽¹⁾	MARKED AS
SN65HVD3080E	DGS, DGSR ⁽²⁾	BTT
SN65HVD3083E		BTU
SN65HVD3086E		BTF

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

(2) The R suffix indicated tape and reel.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

		UNIT
V _{CC}	Supply voltage range ⁽²⁾	–0.3 V to 7 V
V _(A) , V _(B) , V _(Y) , V _(Z)	Voltage range at any bus terminal (A, B, Y, Z)	–9 V to 14 V
V _(TRANS)	Voltage input, transient pulse through 100 Ω. See Figure 10 (A, B, Y, Z)	–50 to 50 V
V _I	Input voltage range (D, DE, RE)	–0.3 V to V _{CC} +0.3 V
P _D	Continuous total power dissipation	See the dissipation rating table
T _J	Junction temperature	170°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

POWER DISSIPATION RATINGS

PACKAGE	T _A < 25°C	DERATING FACTOR ⁽¹⁾ ABOVE T _A < 25°C	T _A = 85°C
DGS-10	463 mW	3.71 mW/°C	241 mW

(1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

ELECTROSTATIC DISCHARGE PROTECTION

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Human Body Model ⁽¹⁾	A,B,Y,Z, and GND		16k		V
	All pins		6k		V
Field-induced-Charged Device Mode ⁽²⁾	All pins		1.5k		V
Machine Model			200		V

(1) Tested in accordance JEDEC Standard 22, Test Method A114-A. Bus pin stressed with respect to a common connection of GND and V_{CC}.

(2) Tested in accordance JEDEC Standard 22, Test Method C101.

SUPPLY CURRENT

over recommended operating conditions unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC} Supply current	\overline{RE} at 0 V, D and DE at V_{CC} , No load	Receiver enabled, Driver enabled		375	750	μA
	\overline{RE} at 0 V, D and DE at 0 V, No load	Receiver enabled, Driver disabled		300	680	μA
	\overline{RE} at V_{CC} , D and DE at V_{CC} , No load	Receiver disabled, Driver enabled		240	600	μA
	\overline{RE} at V_{CC} , D and DE at 0 V, No load	Receiver disabled, Driver disabled		2	1000	nA

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range unless otherwise noted

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_I or V_{IC}	Voltage at any bus terminal (separately or common mode)		-7 ⁽¹⁾		12	
V_{IH}	High-level input voltage	D, DE, \overline{RE}	2		V_{CC}	V
V_{IL}	Low-level input voltage	D, DE, \overline{RE}	0		0.8	
V_{ID}	Differential input voltage		-12		12	
I_{OH}	High-level output current	Driver	-60			mA
		Receiver	-10			
I_{OL}	Low-level output current	Driver			60	mA
		Receiver			10	
T_J	Junction temperature				150	$^{\circ}C$
T_A	Ambient still-air temperature		-40		85	

(1) The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

DRIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OD}	Differential output voltage	No load, I _O = 0	3	4.3	V _{CC}	V
		R _L = 54 Ω, See Figure 1	1.5	2.3		
		V _{test} = -7 V to 12 V, See Figure 2	1.5			
		R _L = 100 Ω, See Figure 1	2			
Δ V _{OD}	Change in magnitude of differential output voltage	R _L = 54 Ω, See Figure 1 and Figure 2	-0.2	0	0.2	V
V _{OC(SS)}	Steady-state common-mode output voltage	See Figure 3	1	2.6	3	V
ΔV _{OC(SS)}	Common-mode output voltage (Dominant)		-0.1	0	0.1	
V _{OC(PP)}	Peak-to-peak common-mode output voltage			0.5		
I _{Z(Y)} or I _{Z(Z)}	High-impedance state output current	V _{CC} = 0 V, V _(Z) or V _(Y) = 12 V Other input at 0 V			1	μA
		V _{CC} = 0 V, V _(Z) or V _(Y) = -7 V Other input at 0 V	-1			
		V _{CC} = 5 V, V _(Z) or V _(Y) = 12 V Other input at 0 V			1	
		V _{CC} = 5 V, V _(Z) or V _(Y) = -7 V Other input at 0 V	-1			
I _I	Input current	D, DE	-100		100	μA
I _{OS}	Short-circuit output current	-7 V ≤ V _O ≤ 12 V	-250		250	mA

DRIVER SWITCHING CHARACTERISTICS

over recommended operating conditions unless otherwise noted

PARAMETER ⁽¹⁾		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH} , t _{PHL}	Propagation delay time, low-to-high-level output Propagation delay time, high-to-low-level output	HVD3080E		0.7	1.3	μs
		HVD3083E		150	500	ns
		HVD3086E		12	20	ns
t _r , t _f	Differential output signal rise time Differential output signal fall time	HVD3080E	0.5	0.9	1.5	μs
		HVD3083E		200	300	ns
		HVD3086E		7	15	ns
t _{sk(p)}	Pulse skew (t _{PHL} - t _{PLH})	HVD3080E		20	200	ns
		HVD3083E		5	50	ns
		HVD3086E		1.4	5	ns
t _{PZH}	Propagation delay time, high-impedance-to-high-level output	HVD3080E		2.5	7	μs
		HVD3083E		1	2.5	μs
		HVD3086E		13	30	ns
t _{PHZ}	Propagation delay time, high-level-to-high-impedance output	HVD3080E		80	200	ns
		HVD3083E		60	100	ns
		HVD3086E		12	30	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output	HVD3080E		2.5	7	μs
		HVD3083E		1	2.5	μs
		HVD3086E		13	30	ns
t _{PLZ}	Propagation delay time, low-level-to-high-impedance output	HVD3080E		80	200	ns
		HVD3083E		60	100	ns
		HVD3086E		12	30	ns
t _{PZH} , t _{PZL}	Propagation delay time, standby-to-high-level output (See Figure 5) Propagation delay time, standby-to-low-level output (See Figure 6)	R _L = 110 Ω, \overline{RE} at 3 V		3.5	7	μs

(1) SNHVD3080 and SNHVD3083 are in the *Product Preview* state of development.

RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IT+}	Positive-going differential input threshold voltage	$I_O = -10$ mA	-0.08		-0.01	V
V_{IT-}	Negative-going differential input threshold voltage	$I_O = 10$ mA	-0.2	-0.1		
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)			30		mV
V_{OH}	High-level output voltage	$V_{ID} = 200$ mV, $I_{OH} = -10$ mA, See Figure 7 and Figure 8	4	4.6		V
V_{OL}	Low-level output voltage	$V_{ID} = -200$ mV, $I_{OH} = 10$ mA, See Figure 7 and Figure 8	0.15		0.4	V
I_{OZ}	High-impedance-state output current	$V_O = 0$ or V_{CC}	-1		1	μ A
I_I	Bus input current	Other input at 0V	V_A or $V_B = 12$ V		0.04	0.11
			V_A or $V_B = 12$ V, $V_{CC} = 0$ V		0.06	0.13
			V_A or $V_B = -7$ V		-0.1	-0.04
			V_A or $V_B = -7$ V, $V_{CC} = 0$ V		-0.05	-0.03
I_{IH}	High-level input current	$V_{IH} = 2$ V	-60	-30		μ A
I_{IL}	Low-level input current	$V_{IL} = 0.8$ V	-60	-30		μ A
C_{ID}	Differential input capacitance	$V_I = 0.4 \sin(4E6\pi t) + 0.5$ V		7		pF

(1) All typical values are at 25°C and with a 3.3-V supply.

RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	$V_{ID} = -1.5$ V to 1.5 V, $C_L = 15$ pF, See Figure 8		75	100	ns
t_{PHL}	Propagation delay time, high-to-low-level output			79	100	
$t_{sk(p)}$	Pulse skew ($ t_{PHL} - t_{PLH} $)			4	10	
t_r	Output signal rise time			1.5	3	
t_f	Output signal fall time			1.8	3	
t_{PZH}	Output disable time to high level	DE at 5 V, See Figure 9		5	50	ns
		From standby		1.6	3.5	μ s
t_{PHZ}	Output enable time from high level	DE at 5 V, See Figure 9		5	50	ns
t_{PZL}	Output disable time to low level	DE at 0 V, See Figure 9		10	50	ns
		From standby		1.7	3.5	μ s
t_{PLZ}	Output enable time from low level	DE at 5 V, See Figure 9		8	50	ns

PARAMETER MEASUREMENT INFORMATION

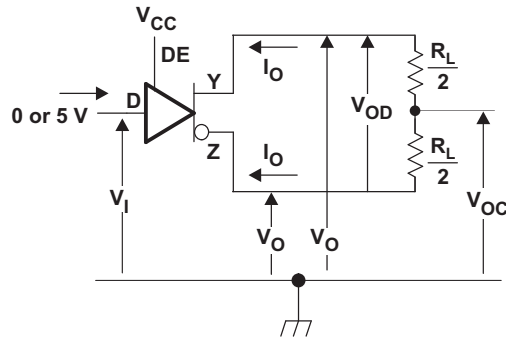


Figure 1. Driver V_{OD} Test Circuit and Current Definitions

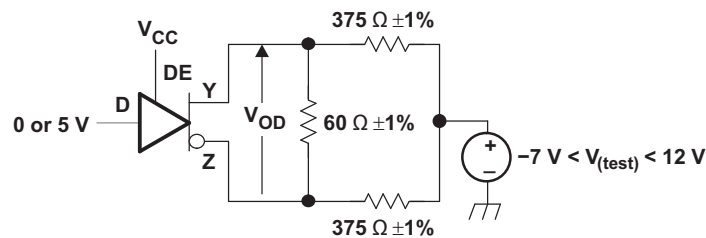


Figure 2. Driver V_{OD} With Common-Mode Loading Test Circuit

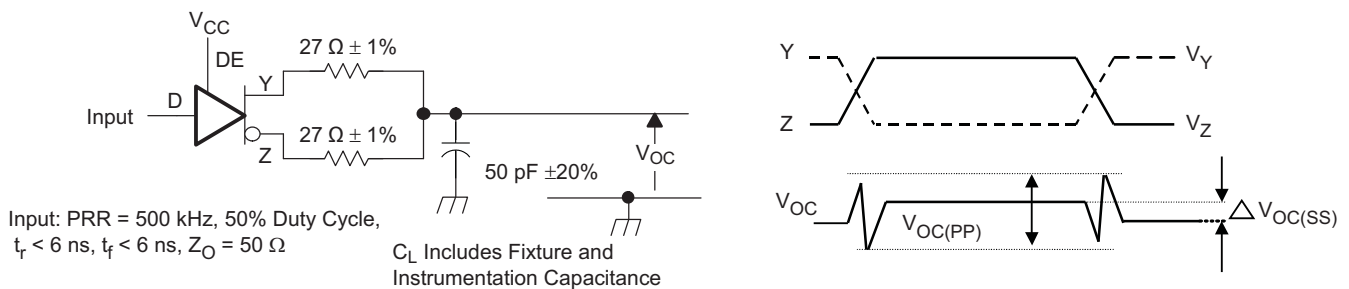


Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage

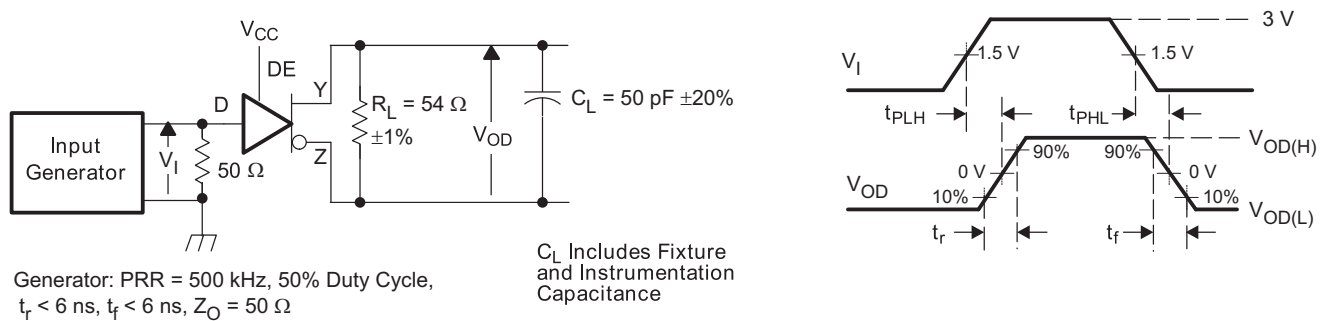


Figure 4. Driver Switching Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

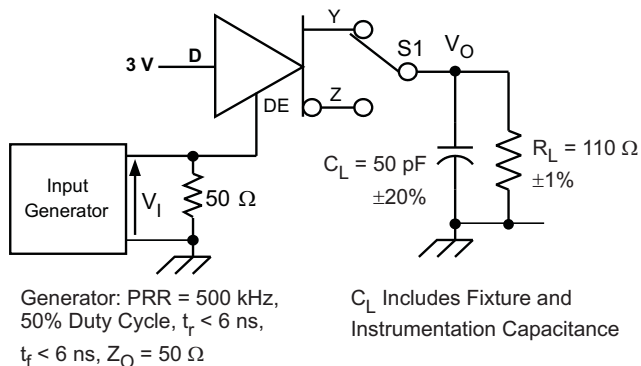


Figure 5. Driver High-Level Output Enable and Disable Time Test Circuit and Voltage Waveforms

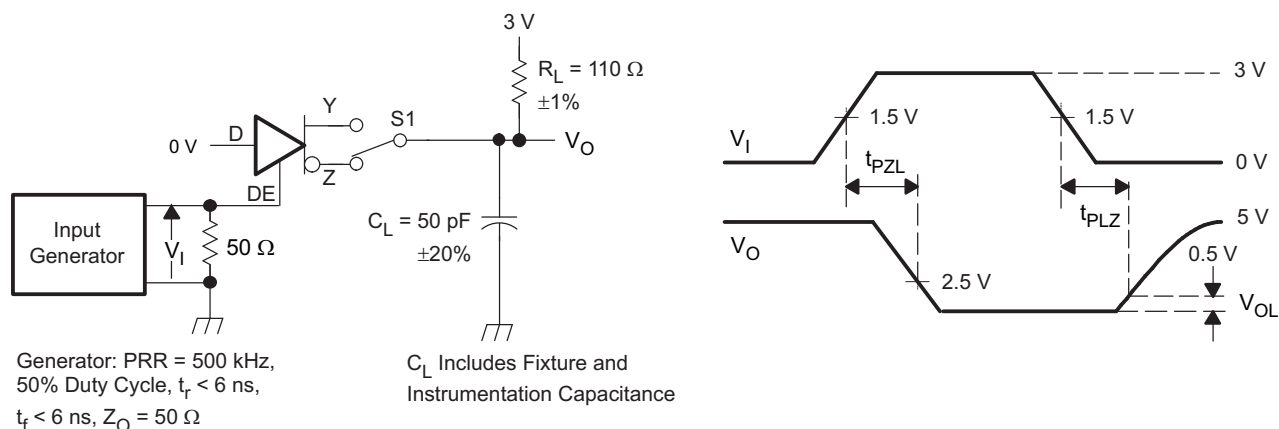


Figure 6. Driver Low-Level Output Enable and Disable Time Test Circuit and Voltage Waveforms

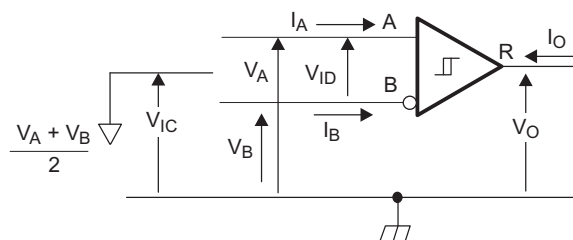


Figure 7. Receiver Voltage and Current Definitions

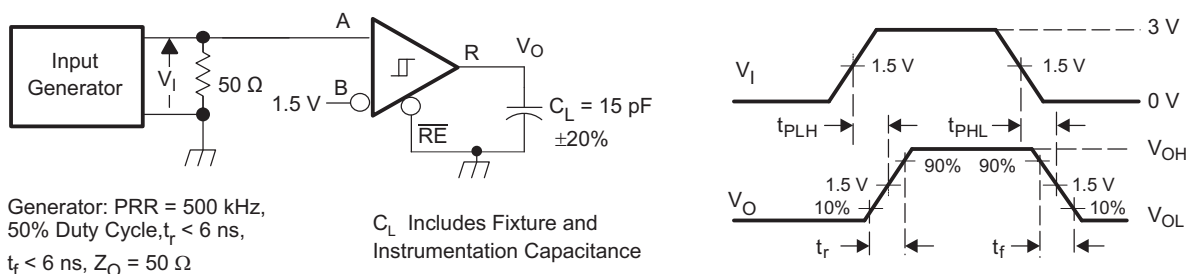


Figure 8. Receiver Switching Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

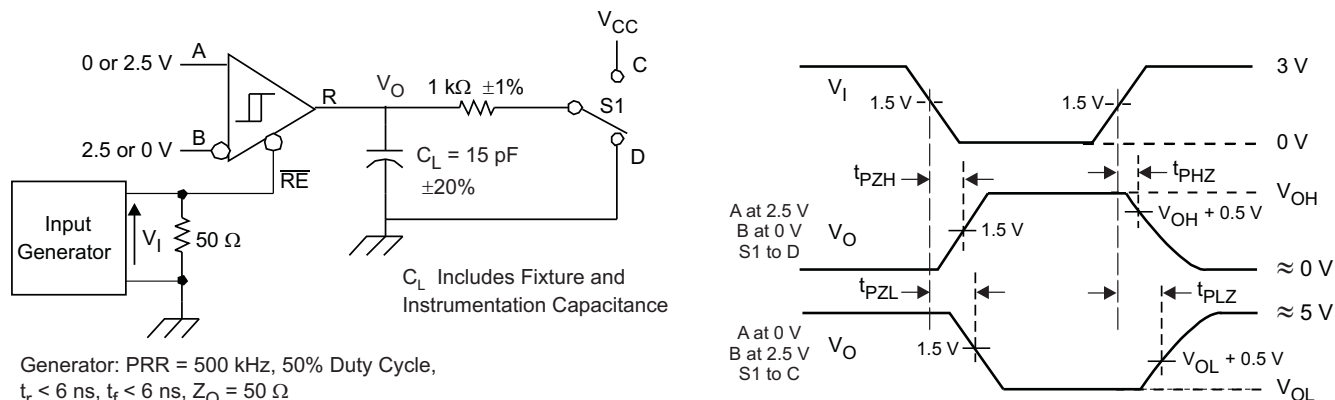
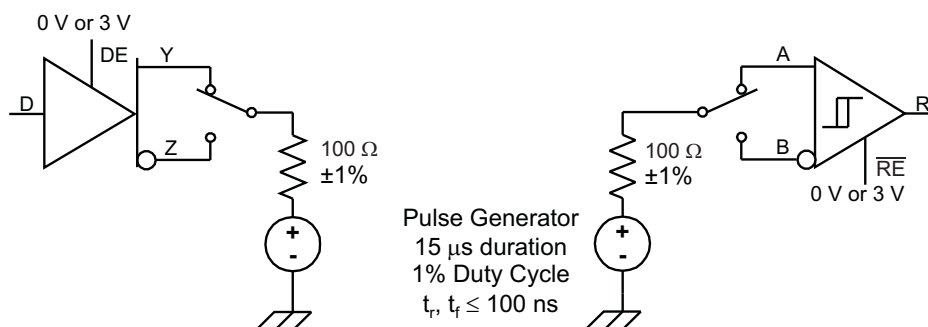


Figure 9. Receiver Enable and Disable Test Circuit and Voltage Waveforms



A. This test is conducted to test survivability only. Data stability at the R output is not specified.

Figure 10. Transient Overvoltage Test Circuit

DEVICE INFORMATION

FUNCTION TABLES

DRIVER⁽¹⁾

INPUT	Enable	OUTPUTS	
D	DE	Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z
Open	H	H	L

(1) H = high level, L = low level, Z = high impedance, X = irrelevant, ? = indeterminate

RECEIVER⁽¹⁾

DIFFERENTIAL INPUTS $V_{ID} = V_{(A)} - V_{(B)}$	ENABLE RE	OUTPUT R
$V_{ID} \leq -0.2 \text{ V}$	L	L
$-0.2 \text{ V} < V_{ID} < -0.01 \text{ V}$	L	?
$-0.01 \text{ V} \leq V_{ID}$	L	H
X	H	Z
Open Circuit	L	H
BUS Idle	L	H
Short Circuit	L	H

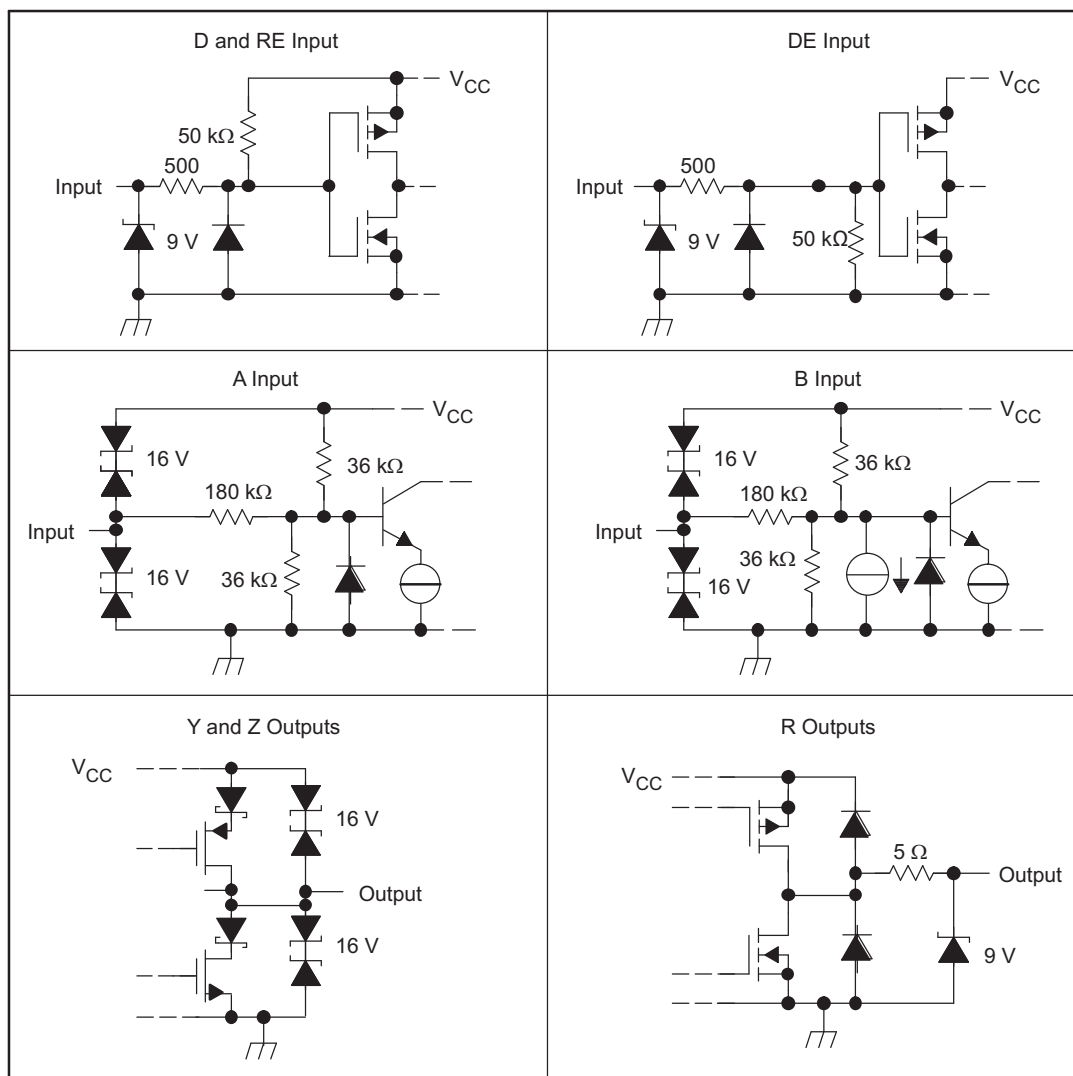
(1) H = high level, L = low level, Z = high impedance, X = irrelevant, ? = indeterminate

DEVICE ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$P_{(AVG)}$	Average power dissipation	$R_L = 60 \Omega$, Input to D a 500-kHz 50% duty cycle square-wave	85	109	136	mW

Equivalent Input and Output Schematic Diagrams



TYPICAL CHARACTERISTICS

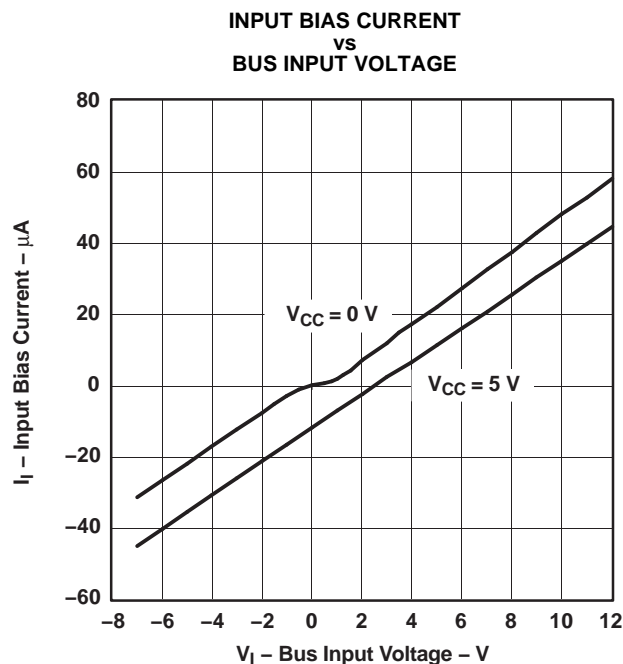


Figure 11.

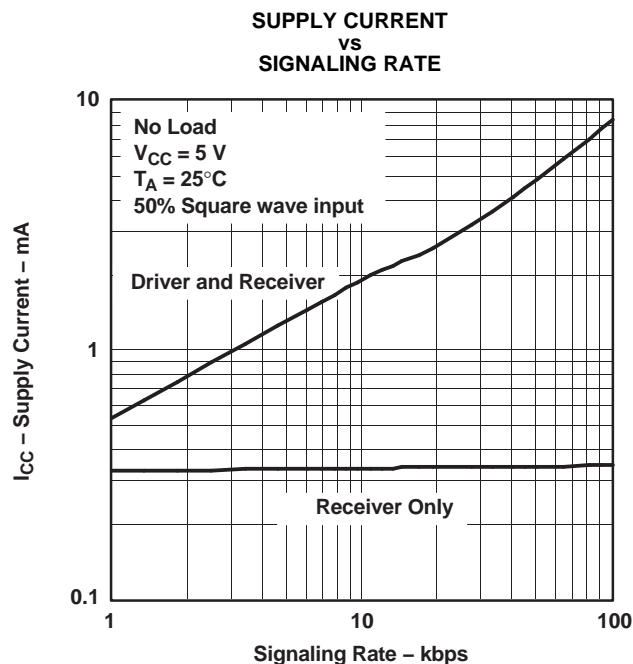


Figure 12.

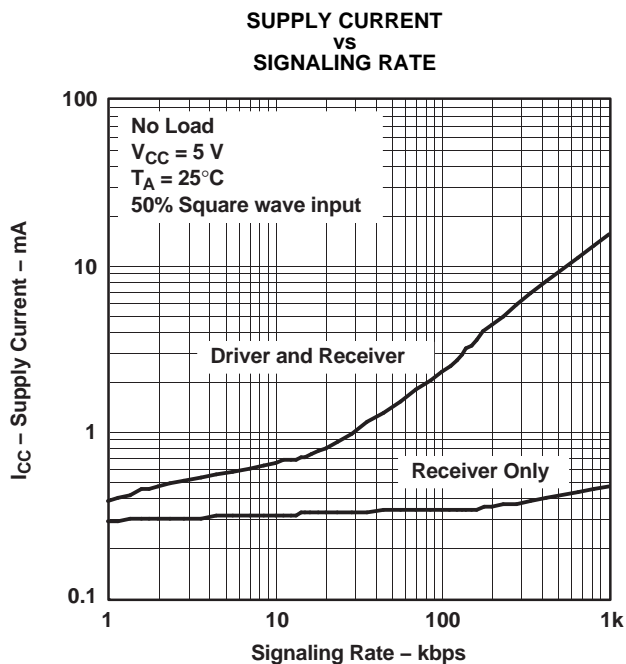


Figure 13.

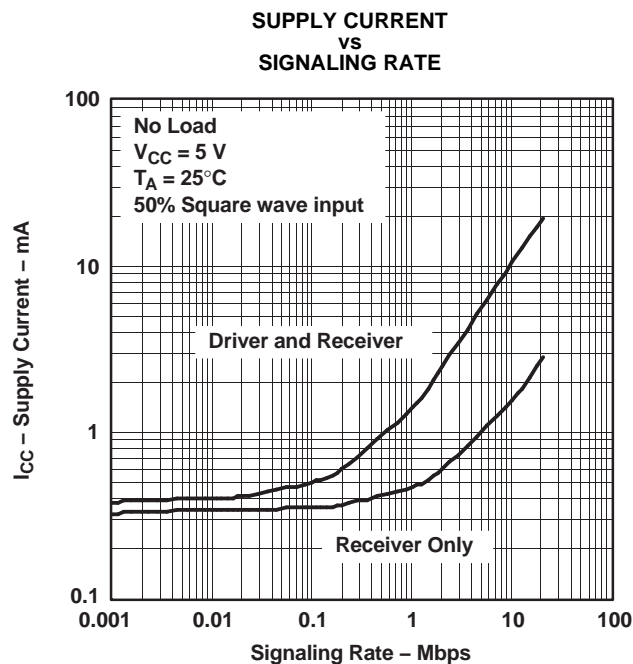


Figure 14.

TYPICAL CHARACTERISTICS (continued)

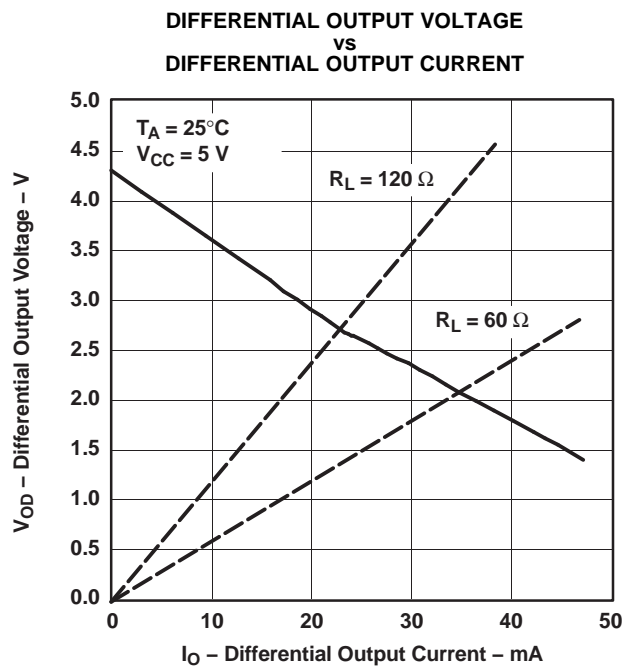


Figure 15.

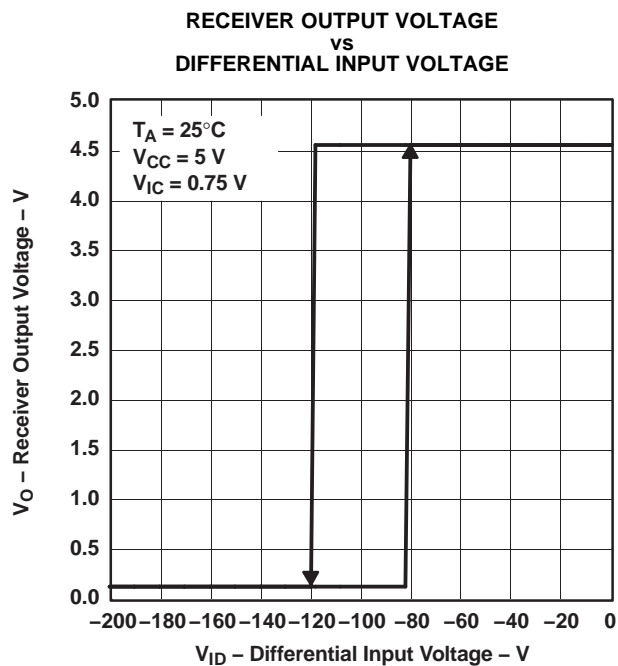


Figure 16.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65HVD3080EDGS	ACTIVE	MSOP	DGS	10	80	TBD	Call TI	Call TI
SN65HVD3080EDGSR	ACTIVE	MSOP	DGS	10	2500	TBD	Call TI	Call TI
SN65HVD3083EDGS	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65HVD3083EDGSG4	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65HVD3083EDGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65HVD3083EDGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65HVD3086EDGS	ACTIVE	MSOP	DGS	10	80	TBD	Call TI	Call TI
SN65HVD3086EDGSR	ACTIVE	MSOP	DGS	10	2500	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



4073272/C 02/04

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-187 variation BA.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265